

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-2. (Canceled)

3. (Previously Presented) The manufacturing process of conductive composition as in claim 11, wherein said first slurry and said second slurry have substantially the same composition.

4-10. (Canceled)

11. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and
colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry,

wherein an average particle size of said metal particles is $0.5\mu\text{m}$ or less,
andless,

anwherein an average particle size of said ceramic particles is a quarter of or less than the average particle size of said metal particlessparticles, and

wherein said metal particles are wetted by a liquid solvent that is compatible with an organic component included in said conductive composition and is incompatible with water.

12. (Canceled)

13. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry,

wherein an average particle size of said ceramics particles is less than that of said metal particles, and particles,

wherein an average particle size of said metal particles is $0.5\mu\text{m}$ or less, less,
and

wherein said metal particles are wetted by a liquid solvent that is compatible
with an organic component included in said conductive composition and is incompatible with
water.

14. (Canceled)

15. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and
colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry,

wherein said metal particles are Ni or Ni content compound, and
an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles, particles,

wherein said metal particles are wetted by a liquid solvent that is compatible
with an organic component included in said conductive composition and is incompatible with
water.

16. (Canceled)

17. (Previously Presented) The manufacturing process of conductive composition as in claim 11, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

18-25. (Canceled)

26. (Previously Presented) The manufacturing process of conductive composition as in claim 15, wherein said first slurry and said second slurry have substantially the same composition.

27-29. (Canceled)

30. (Previously Presented) The manufacturing process of conductive composition as in claim 15, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.
electrode on ceramic dielectric substrate.

31-32. (Canceled)

33. (Previously Presented) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed, and
colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along relatively different direction from the first slurry,

wherein an average particle size of said metal particles is 0.5 μm or less; and
a liquid for wetting said metal particles is a solvent being compatible with an organic component included in said conductive composition and incompatible with water.

34. (Previously Presented) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed, and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along relatively different direction from the first slurry,

wherein said metal particles are Ni or Ni content compound; and
a liquid for wetting said metal particles is a solvent being compatible with an organic component included in said conductive composition and incompatible with water.